

[54] **SHEET-METAL HEAT SINK FOR ELECTRONIC SEMICONDUCTOR DEVICES**

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[**] **Term:** 14 Years

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[52] **U.S. Cl.** D13/23
[58] **Field of Search** D13/23; 174/16 HS;
357/81; 165/80, 80 A, 80 B

[56] **References Cited**
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3,694,703 9/1972 Wilkens et al. 174/16 HS X

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[57] **CLAIM**

The ornamental design for a sheet-metal heat sink for electronic semiconductor devices, substantially as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a sheet-metal heat sink for electronic semiconductor devices showing my new design; the broken lines being shown for illustrative purposes, only;
FIG. 2 is a front elevational view of the same heat sink;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a side elevational view thereof, looking toward the right side of the heat sink as it is shown in FIG. 1;
FIG. 5 is a side elevational view thereof, looking toward the left side of the heat sink as it is shown in FIG. 1;
FIG. 6 is a top plan view thereof; and
FIG. 7 is a bottom plan view thereof.

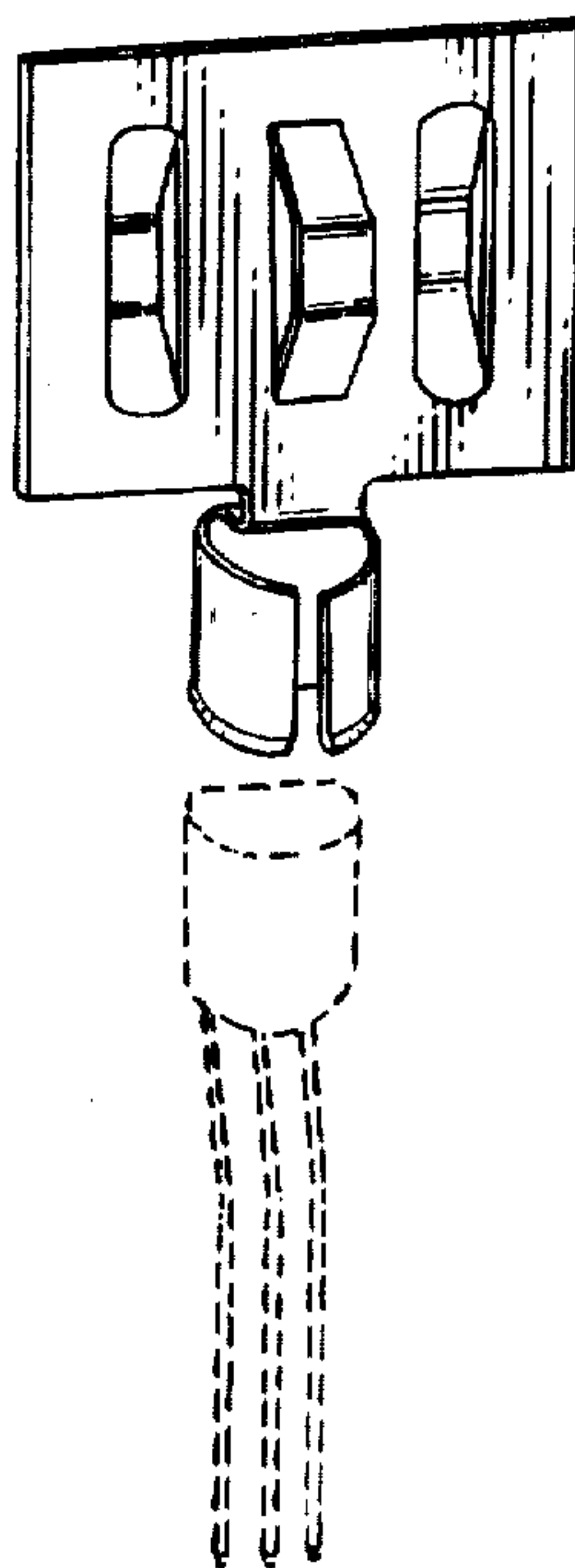


FIG. 1

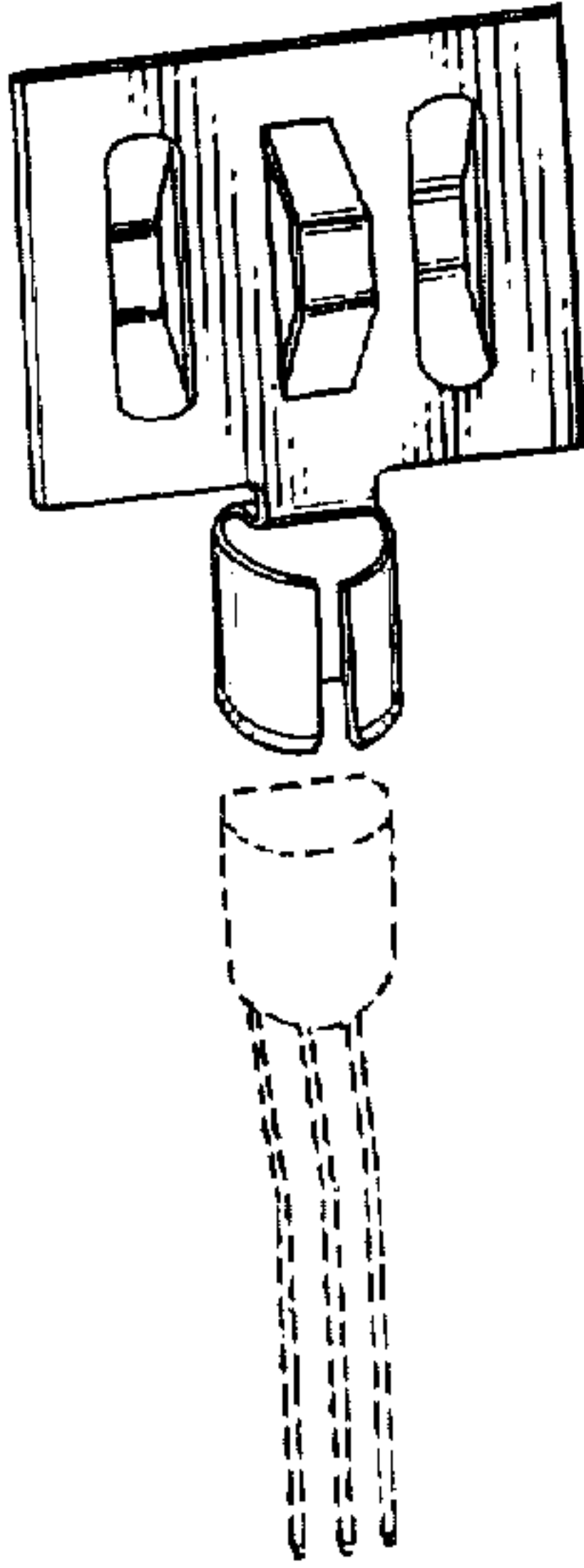


FIG. 2

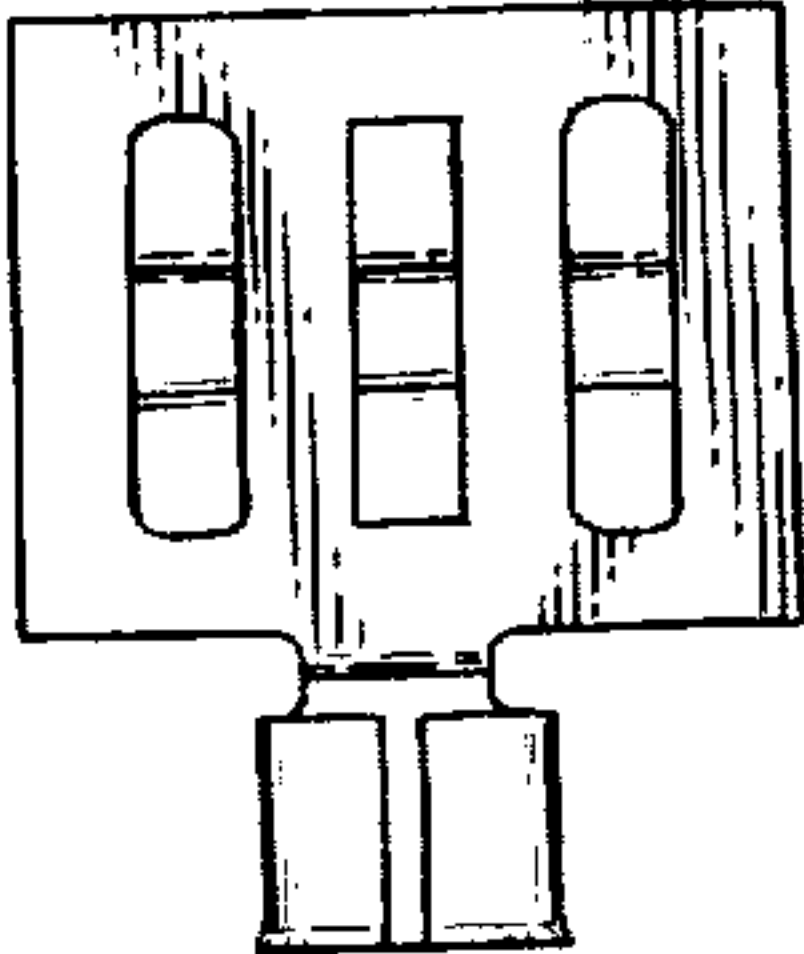


FIG. 3

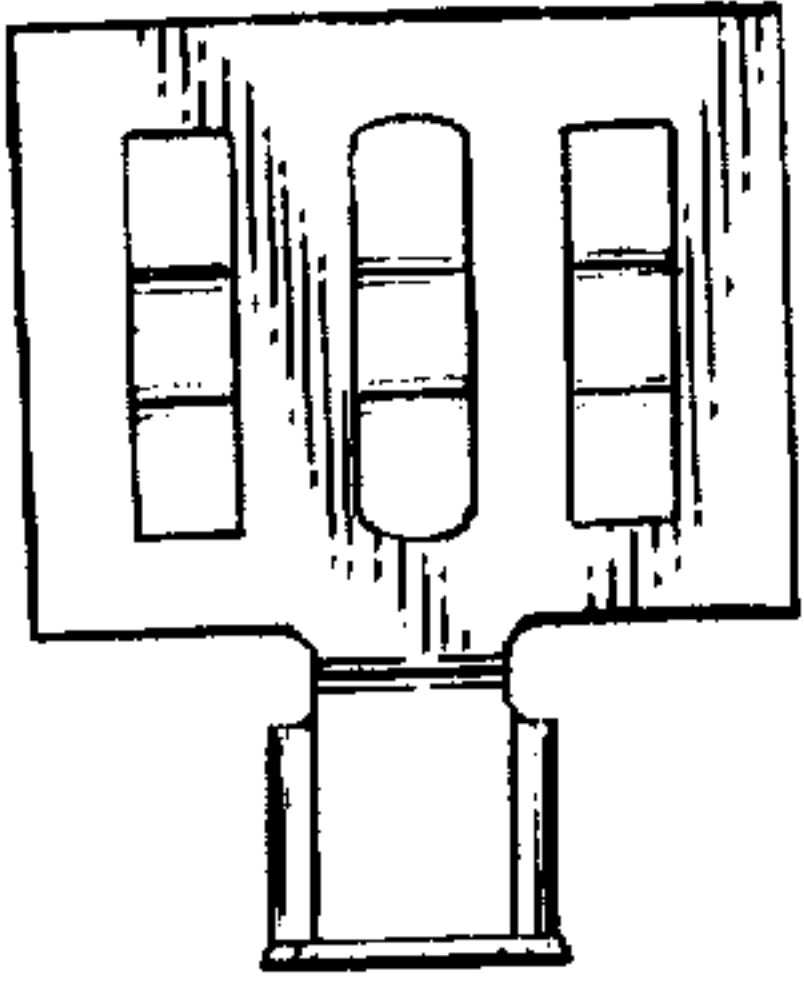


FIG. 4

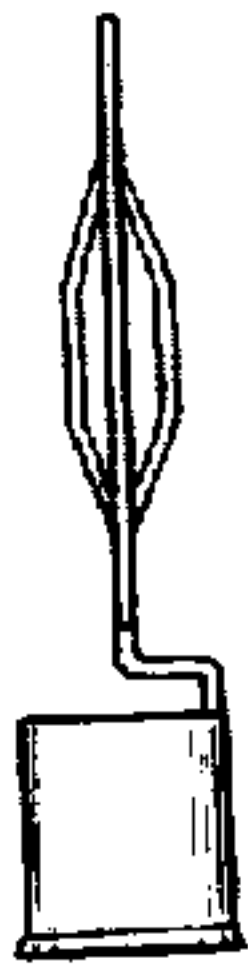


FIG. 5

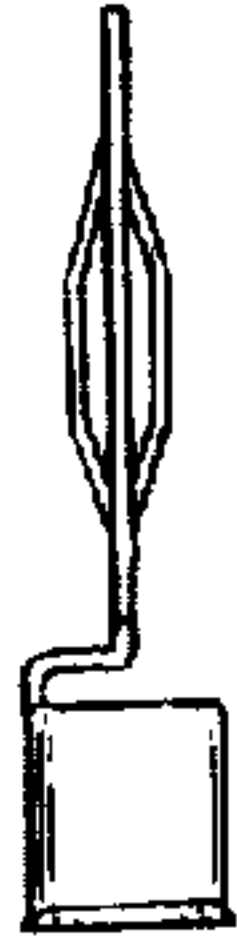


FIG. 6



FIG. 7

